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(54) RELEASE LAYER FOR METAL FOIL WITH CARRIER AND METAL FOIL COMPRISING THE SAME

(71) Applicant: YMT CO., LTD., Incheon (KR)

(72) Inventors: Sung Wook CHUN, Incheon (KR); Bo Mook CHUNG, Incheon (KR); Dea

> Geun KIM, Incheon (KR); Myong Hwan PARK, Incheon (KR); Nak Eun KO, Bucheon-si (KR); Ju Yong SIM,

Seoul (KR)

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(57) ABSTRACT

The present invention relates to a release layer for a metal foil with carrier and a metal foil with carrier including the release layer. The release layer is designed for easy removal of the carrier and includes one or more nitrogenous heterocyclic compounds and one or more inorganic compounds containing at least one metal selected from the group consisting of nickel, molybdenum, cobalt, phosphorus, manganese, and iron.

